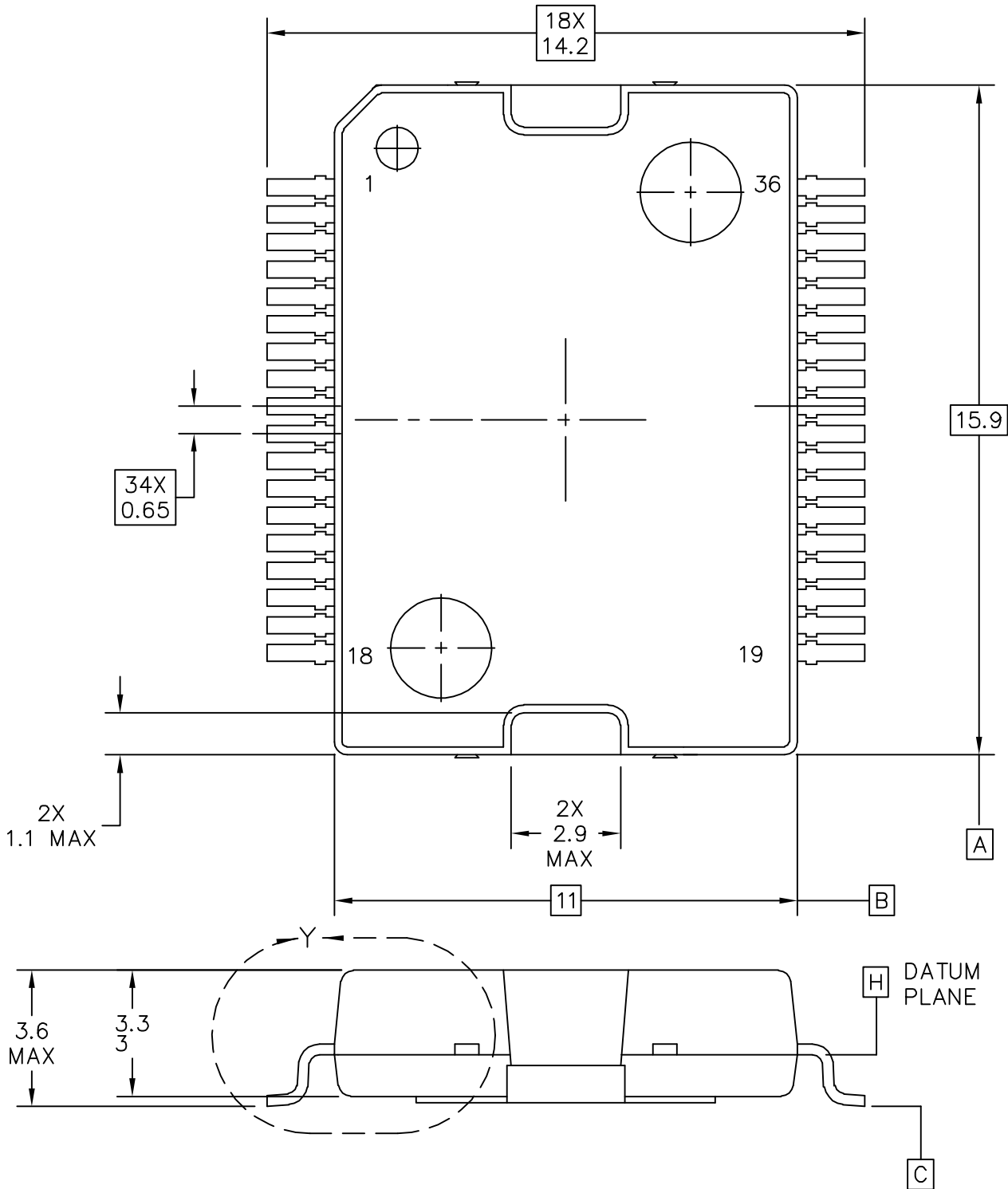




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MECHANICAL OUTLINE

DO NOT SCALE THIS DRAWING



TITLE:
36 LEAD HSOP
W/PROTRUDING HEATSINK

DOCUMENT NO: 98ASA10522D REV: C

STANDARD: NON-JEDEC

SOT1578-1

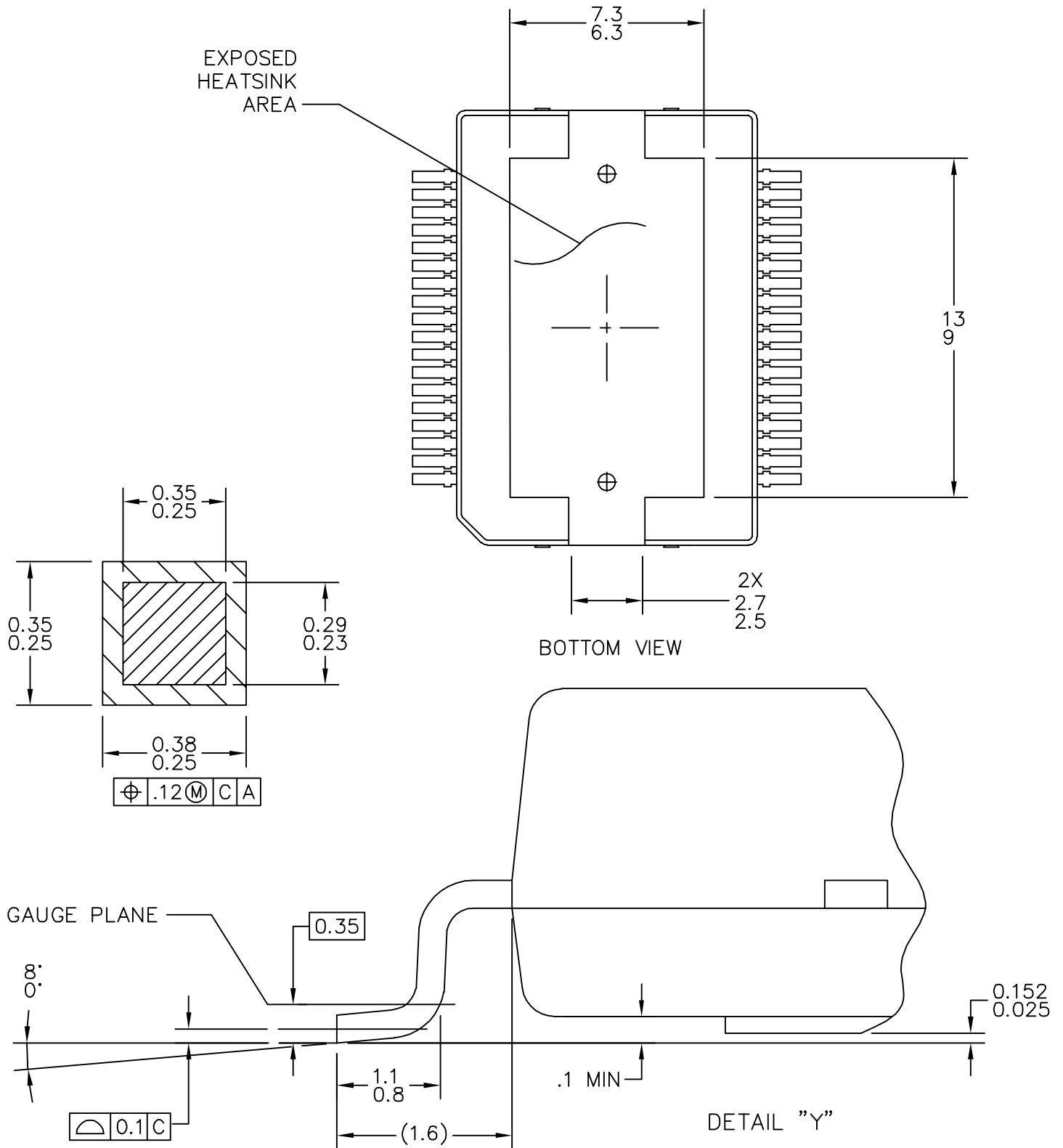
SHEET: 1 OF 4



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MECHANICAL OUTLINE

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TITLE: 36 LEAD HSOP
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SHEET:

2



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MECHANICAL OUTLINE

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NOTES:

1. CONTROLLING DIMENSION: MILLIMETER
2. DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DATUM PLANE -H- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.15 PER SIDE. DIMENSIONS "D" AND "E1" DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
5. DIMENSION "b" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 TOTAL IN EXCESS OF THE "b" DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. DATUMS -A- AND -B- TO BE DETERMINED AT DATUM PLANE -H-.
7. DIMENSIONS "D" DOES NOT INCLUDE TIEBAR PROTRUSIONS. ALLOWABLE TIEBAR PROTRUSIONS ARE 0.15 PER SIDE.

TITLE:
 36 LEAD HSOP
 W/PROTRUDING HEATSINK

DOCUMENT NO: 98ASA10522D	REV: C
STANDARD: NON-JEDEC	
SOT1578-1	SHEET: 3



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REVISION HISTORY

LTR	ORIGINATOR	REVISIONS	DRAFTER	DATE
0	F. MOSNA	RELEASED FOR PRODUCTION	WS	01 FEB 2002
A	R. SHUMWAY	SHEET 2: REMOVED THE CHAMFERS IN THE CORNERS OF THE EXPOSED HEATSINK. REMOVED THE RELATED DIMENSION, "4X 1 MAX". UPDATED TO FSL LOGO.	JO LIM	17 DEC 04
B	R. SHUMWAY	SHEET 1: CHANGED PIN NUMBERING ASSIGNMENT FROM "1,15,16,30" TO "1,18,19,36".	KL CHIN	17 FEB 05
C	C. SUN	UPDATED LOGO TO NXP (DAR #25617)	CS	11 MAR 2016

TITLE: 36 LEAD HSOP
W/PROTRUDING HEATSINK

DOCUMENT NO: 98ASA10522D REV: C

STANDARD: NON-JEDEC

SOT1578-1 SHEET: 4